

01-05-2009



U.S. DEPARTMENT OF COMMERCE

12/30/08 1035	42164	
To the Honorable Assistant Secretary and Commissioner of Patents and Tradem	narks: Please record the attached original document(s) or copy(ies) thereof.	
Name of conveying party(ies):	2. Name and address of receiving party(ies):	
UBE NITTO KASEI CO., LTD.	Name: HONDA MOTOR CO., LTD.	
Additional name(s) of conveying party(ies) attached? NO	Address: 1-1, Minami Aoyama 2-chome, Minato-ku, Tokyo	
3. Nature of conveyance:	107-8556 Japan	
X Assignment Merger Security Agreement Change of Name Other Execution Date: December 2, 2008	Additional name(s) & address(es) attached? NO	
4. Application number(s) or patent number(s):		
If this document is being filed together with a new application, the exect A. Patent Application No.(s) 10/509,225, filed February 8, 2005 Additional number	B. Patent No.(s)	
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1	
Name: WENDEROTH, LIND & PONACK, L.L.P. Attn: Kenneth W. Fields, Esq.	7. Total fee (37 CFR 3.41)\$40.00 X Enclosed (Check No. 77)	
Street Address: 2033 K Street, N.W., Suite 800	Authorized to be charged to deposit account	
· City: Washington, State: DC ZIP: 20006-1021	8. Deposit account number: 23-0975	
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	The divide	
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.		
Kenneth W. Fields, Reg. No. 52,430 Name of Person Signing Signature	Date	
OMB No. 0651-0011 (exp. 4/94)	Total number of pages including cover sheet: 3	
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Public burden reporting for this sample cover sheet is estimated to average about document and gathering the data needed, and completing and reviewing the sam Patent and Trademark Office, Office of Information Systems, PK2-1000C, Was Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.	nple cover sheet. Send comments regarding this burden estimate to the U.S.	
	DOCKET NO. 2004_1533A	

The Commissioner is authorized to charge any deficiency or to credit any overpayment associated with this communication to Deposit Account No. 23-0975, with the EXCEPTION of deficiencies in fees for multiple dependent claims in new applications.

> **PATENT REEL: 022054 FRAME: 0310**

ASSIGNMENT

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR: UBE NITTO KASEI CO., LTD.

1-7, Higashi-Nihonbashi 1-chome, Chuo-ku, Tokyo 103-0004 Japan

to whom Assignments were recorded on February 8, 2005 and September 26, 2007 at Reel 016241, Frame 0099, and Reel 019915, Frame 0140, respectively,

hereby sells, assigns and transfers to

ASSIGNEE: HONDA MOTOR CO., LTD.

1-1, Minami Aoyama 2-chome, Minato-ku, Tokyo, 107-8556 Japan

to whom an Assignment was recorded on September 26, 2007 at Reel 019915, Frame 0140,

and the successors, assigns and legal representatives of the ASSIGNEE, an additional undivided 25% interest for the United States and its territorial possessions in and to any and all improvements which are disclosed in the invention entitled: HOLLOW STRUCTURE PLATE, MANUFACTURING METHOD THEREOF, MANUFACTURING DEVICE THEREOF, AND SOUND ABSORBING STRUCTURE PLATE

and which is found in U.S. Patent Application Serial No. 10/509,225 (hereafter "Application"), filed February 8, 2005, such that UBE NITTO KASEI CO., LTD. and HONDA MOTOR CO., LTD. now each own an undivided 50% interest in said Application. This Assignment document applies only to said Application, and not to any continuation and/or divisional applications of said Application.

The ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

The ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided with all pertinent facts and documents relating to said invention and said application and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and Letters Patent resulting from said application, and said equivalents thereof which may be necessary or desirable to carry out the purpose thereof;

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, D.C. 20006-1021, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordal of this document.

IN witness whereof, I/WE have hereunto set hand and seal this <u>62, Pecember, 2008</u>.

(Date of signing)

Shinichiri Jamanoto
(Signature of person authorized to sign on behalf of ASSIGNOR)

Shinichiro Yamamoto

(type or print the name of person who signs above)

President

(Official Title of person who signs above)

PATENT REEL: 022054 FRAME: 0311

Witness	Toshiyaki Taachi	
Witness	Toshiyaki Taachi Tomofumi Shimon	ura
	ACKNOWLEDGME	NT .
	} ss	
This	day of	, 20, before me
	bove-named	
		secuted the foregoing assignment, who as (their) own free will for the purposes
		recuted the foregoing assignment, who is (their) own free will for the purposes
did acknowledge to m		
did acknowledge to m therein set forth.		nis (their) own free will for the purposes
did acknowledge to m therein set forth.		Official Signature
did acknowledge to m therein set forth. SEAL		Official Signature Official Title
did acknowledge to m therein set forth. SEAL The above appli	e that he (they) executed the same of h	Official Signature Official Title

Title of Invention HOLLOW STRUCTURE PLATE, MANUFACTURING METHOD THEREOF, MANUFACTURING DEVICE THEREOF, AND SOUND ABSORBING STRUCTURE PLATE

PATENT RECORDED: 12/30/2008 REEL: 022054 FRAME: 0312